| L Number | Hits      | Search Text  | DB                                      | Time stamp                        |
|----------|-----------|--|---|-----------------------------------|
| - Hammet | 909       | ((mold near2 (upper lower)) and  | USPAT;                                  | 2003/03/27 09:37                  |
|          | 1         | semiconductor and (chip die wafer)) and  | US-PGPUB;                               |                                   |
|          |           | (methor process)   | EPO; JPO;                               |                                   |
|          | 1.50      | ///mald manual //ware 3  | DERWENT                                 | 2002/00/20 00 57                  |
| _        | 468       | (((mold near2 (upper lower)) and semiconductor and (chip die wafer)) and                 | USPAT;<br>US-PGPUB;                     | 2002/09/20 09:57                  |
|          |           | (methor process)) and (inject injecting  | EPO; JPO;                               |                                   |
| 1        |           | injected)  | DERWENT                                 |                                   |
| _        | 403       | ((((mold near2 (upper lower)) and  | USPAT;                                  | 2002/09/20 09:58                  |
|          |           | semiconductor and (chip die wafer)) and  | US-PGPUB;                               |                                   |
|          |           | (methor process)) and (inject injecting  | EPO; JPO;                               |                                   |
|          | 1         | <pre>injected)) and (resin encapsulant sealing) (((((mold near2 (upper lower)) and</pre> | DERWENT<br>USPAT;                       | 2002/09/20 10:08                  |
|          | 1         | semiconductor and (chip die wafer)) and  | US-PGPUB;                               | 2002/03/20 10:00                  |
|          |           | (methor process)) and (inject injecting  | EPO; JPO;                               | 1                                 |
| }        |           | injected)) and (resin encapsulant  | DERWENT                                 |                                   |
|          |           | sealing)) and ((releasable released  |   |                                   |
|          | 101       | releasing) near1 (layer film material))  | *************************************** | 2000/00/00 10 00                  |
| -        | 101       | (((((mold near2 (upper lower)) and semiconductor and (chip die wafer)) and               | USPAT;<br>US-PGPUB;                     | 2002/09/20 10:03                  |
|          |           | (methor process)) and (inject injecting  | EPO; JPO;                               |                                   |
|          |           | injected)) and (resin encapsulant  | DERWENT                                 |                                   |
|          |           | sealing)) and (releasable released   | İ                                       |                                   |
|          |           | releasing)   |   | 0000 (00 (07 11 17                |
| -        | 63        | ((((((mold near2 (upper lower)) and  | USPAT;                                  | 2003/03/27 11:06                  |
|          |           | semiconductor and (chip die wafer)) and (methor process)) and (inject injecting          | US-PGPUB;<br>EPO; JPO;                  |                                   |
|          |           | injected)) and (resin encapsulant  | DERWENT                                 | (                                 |
|          |           | sealing)) and (releasable released   |   |                                   |
|          |           | releasing)) and ((flipchip (flip adj   |   |                                   |
| 1 .      | 170       | chip)) bump ball)  |   | 2222 /22 /22 /2                   |
| -        | 179       | (mold near2 (upper lower)) and ((releasable released releasing) near1                    | USPAT;<br>US-PGPUB;                     | 2002/09/20 10:10                  |
|          |           | (layer film material))   | EPO; JPO;                               |                                   |
|          |           | (layer rim material)   | DERWENT                                 |                                   |
| -        | 12        | ((mold near2 (upper lower)) and  | USPAT;                                  | 2002/09/20 10:27                  |
|          |           | ((releasable released releasing) near1   | US-PGPUB;                               |                                   |
|          |           | (layer film material))) and semiconductor and (chip die wafer)                           | EPO; JPO;                               |                                   |
|          | 0         | 6123895.URPN.  | DERWENT<br>USPAT                        | 2002/09/20 10:16                  |
| -        | 5         | ("3178807"   "5006417"   "5384087"   | USPAT                                   | 2002/09/20 10:16                  |
|          |           | "5616421"   "5902943").PN.   |   |                                   |
| -        | 1         | jp408142106a   | USPAT;                                  | 2002/09/20 10:29                  |
| 1        |           |  | US-PGPUB;<br>EPO; JPO;                  |                                   |
|          |           |  | DERWENT                                 |                                   |
| -        | 156       | MIYAJIMA-FUMIO   | USPAT;                                  | 2002/09/20 10:30                  |
| (        |           | -  | US-PGPUB;                               |                                   |
|          |           |  | EPO; JPO;                               |                                   |
| Ţ        |           | MIND THAD BUMIO  | DERWENT                                 | 2000/00/00 10 55                  |
| _        | 19<br>1   | MIYAJIMA-FUMIO<br>  6187243.pn. and (parting adj face)                                   | USPAT; EPO                              | 2002/09/20 10:30 2002/09/20 14:01 |
| 1 1      | 1         | oro.240.pm. and (parting add race)   | USPAT;<br>US-PGPUB;                     | 2002/03/20 14:01                  |
| ]        |           |  | EPO; JPO;                               |                                   |
| ]        |           |  | DERWENT                                 |                                   |
|          | 1481      | (mold near2 (upper lower)) and   | USPAT;                                  | 2003/05/08 09:42                  |
| ]        |           | semiconductor and (chip die wafer)   | US-PGPUB;                               |                                   |
|          |           |  | EPO; JPO; DERWENT                       | }                                 |
| -        | 39173     | mold near2 (upper lower)   | USPAT;                                  | 2003/03/27 09:34                  |
|          |           | , , , , , , , , , , , , , , , , , , ,  | US-PGPUB;                               |                                   |
|          |           |  | EPO; JPO;                               |                                   |
|          |           | /mald many 2 / mm   2   1   1   2   1   1   1   1   1   1                                | DERWENT                                 | 0000 (00 (0)                      |
| -        | 54        | (mold near2 (upper lower)) near3 (air adj  | USPAT;                                  | 2002/09/24 14:59                  |
|          |           | venc,  | US-PGPUB;<br>EPO; JPO;                  |                                   |
|          |           |  | DERWENT                                 |                                   |
| -        | 8         | ((mold near2 (upper lower)) near3 (air adj   | USPAT;                                  | 2002/09/24 14:59                  |
|          |           | vent)) and semiconductor and (chip die   | US-PGPUB;                               |                                   |
|          |           | wafer)   | EPO; JPO;                               |                                   |
| L        | L <u></u> |  | DERWENT                                 | l <u> </u>                        |

|            | F 6 2 0 | tab ===================================  | TIOD NO.            | 1 2002 (00 (04 15 10 |
|------------|---------|--|---------------------|----------------------|
| -          | 5628    | tab near3 lead   | USPAT;<br>US-PGPUB; | 2002/09/24 15:18     |
| <b>f</b>   | 1       |  | EPO; JPO;           |                      |
|            |         |  | DERWENT             |                      |
| <b>\</b> _ | 1951    | (tab near3 lead) and semiconductor and   | USPAT;              | 2003/05/19 08:33     |
|            | 1 202   | (chip die wafer)   | US-PGPUB;           | 2003/03/13 00:33     |
|            | }       | (onip die water)   | EPO; JPO;           | F .                  |
|            |         |  | DERWENT             | [                    |
| <b> </b>   | 92      | ((tab near3 lead) and semiconductor and  | USPAT;              | 2003/05/19 08:34     |
|            |         | (chip die wafer)) and ((lead near3 (plated   | US-PGPUB;           |                      |
| 1          |         | plating electroplated electroplating))   | EPO; JPO;           | 1                    |
|            |         | with (electrode terminal pad))   | DERWENT             |                      |
| -          | 21      | ((tab near3 lead) and semiconductor and  | USPAT;              | 2002/09/24 15:29     |
|            | 1       | (chip die wafer)) and ((lead near3 (plated   | US-PGPUB;           |                      |
|            | 1       | plating electroplated electroplating))   | EPO; JPO;           |                      |
|            | 1       | with ((electrode terminal pad) near3 (chip   | DERWENT             |                      |
| ĺ          | Ì       | die ic)))  |                     |                      |
| -          | 3900    | 257/787  | USPAT;              | 2003/02/12 12:29     |
| Ì          | 1       |  | US-PGPUB;           |                      |
|            |         |  | EPO; JPO;           |                      |
|            | 1220    | 257/707 and share  | DERWENT             | 2002/00/12 12        |
| i -        | 1339    | 257/787 and shape  | USPAT;              | 2003/02/12 12:29     |
|            |         |  | US-PGPUB;           |                      |
|            |         |  | EPO; JPO;           | į                    |
| l _        | 57      | (257/787 and shape) and leadless   | DERWENT<br>USPAT:   | 2003/02/12 12:29     |
| [          | [       | (237)707 and Shape) and leadless   | US-PGPUB;           | 2003/02/12 12:29     |
| İ          |         |  | EPO; JPO;           |                      |
| Į i        | l       |  | DERWENT             | l                    |
| i <u>-</u> | 40537   | mold near2 (upper lower)   | USPAT;              | 2003/05/08 09:40     |
| ļ          |         | mora model (appor lower)   | US-PGPUB;           | 2003,03,00           |
|            |         |  | EPO; JPO;           |                      |
| į .        |         |  | DERWENT             | Į                    |
| -          | 7365    | (mold near2 (upper lower) ) and (chip die  | USPAT;              | 2003/03/27 09:37     |
|            |         | wafer)   | US-PGPUB;           |                      |
| ļ          |         |  | EPO; JPO;           |                      |
|            |         |  | DERWENT             |                      |
| -          | 4354    | ((mold near2 (upper lower) ) and (chip die   | USPAT;              | 2003/03/27 09:39     |
|            |         | wafer)) and (methor process)   | US-PGPUB;           |                      |
|            |         |  | EPO; JPO;           |                      |
|            | 5701    |  | DERWENT             |                      |
| ļ -        | 5701    | ((mold near2 (upper lower) ) and (chip die   | USPAT;              | 2003/03/27 09:39     |
|            |         | wafer)) and (method process)   | US-PGPUB;           |                      |
|            |         |  | EPO; JPO;           |                      |
| _          | 173     | (((mold near2 (upper lower) ) and (chip  | DERWENT<br>USPAT;   | 2003/03/27 09:45     |
|            | 1/3     | die wafer)) and (method process)) and  | US-PGPUB;           | 2003/03/2/ 09:45     |
|            |         | (flipchip (flip adj chip))   | EPO; JPO;           |                      |
|            |         | (  | DERWENT             |                      |
| -          | o       | ((((mold near2 (upper lower) ) and (chip   | USPAT;              | 2003/03/27 11:07     |
|            |         | die wafer)) and (method process)) and  | US-PGPUB;           | =:==,==,=,=,=,=      |
|            |         | (flipchip (flip adj chip))) and  | EPO; JPO;           |                      |
|            | l i     | ((relcasable released releasing) near  | DERWENT             |                      |
| ]          | ]       | (film layer tape))   | ]                   |                      |
|            | 12      | ((((mold near2 (upper lower) ) and (chip   | USPAT;              | 2003/03/27 14:36     |
|            | İ       | die wafer)) and (method process)) and  | US-PGPUB;           |                      |
|            |         | (flipchip (flip adj chip))) and  | EPO; JPO;           |                      |
|            |         | ((releasable released release releasing)   | DERWENT             | 1                    |
|            | _ [     | near (film layer tape))  |                     | 0000/00/05           |
| -          | 0       | 20020017738.URPN.  | USPAT               | 2003/03/27 12:20     |
| _          | 55      | ((((mold near2 (upper lower) ) and (chip   | USPAT;              | 2003/03/27 14:35     |
|            |         | die wafer)) and (method process)) and  | US-PGPUB;           |                      |
|            | l       | <pre>(flipchip (flip adj chip))) and (releasable released release releasing)</pre> | EPO; JPO;           |                      |
|            |         | (releasante released lelease Leleasing)  | DERWENT             | L                    |

|          | 43    | (((((mold near2 (upper lower) ) and (chip  | USPAT;                 | 2003/03/27 12:24 |
|----------|-------|--|------------------------|------------------|
| ]        | ]     | die wafer)) and (method process)) and  | US-PGPUB;              | ]                |
| 1        |       | (flipchip (flip adj chip))) and  | EPO; JPO;              |                  |
|          | 1     | (releasable released release releasing))   | DERWENT                | 1                |
|          |       | <pre>not (((((mold near2 (upper lower) ) and<br/>(chip die wafer)) and (method process))</pre> | İ                      |                  |
|          | ļ     | and (flipchip (flip adj chip))) and  |                        |                  |
|          |       | ((releasable released release releasing)   |                        | 1                |
| Į.       | į     | near (film layer tape)))   | 1                      |                  |
| _        | 98    | 5450283.URPN.  | USPAT                  | 2003/03/27 14:35 |
| -        | 759   |  | USPAT                  | 2003/03/27 14:35 |
|          |       | die wafer)) and (method process)) and  |                        |                  |
|          |       | (bump ball)  |                        |                  |
| -        | 671   | ((((mold near2 (upper lower) ) and (chip   | USPAT                  | 2003/03/27 14:35 |
|          |       | die wafer)) and (method process)) and  |                        | 1                |
|          |       | (bump ball)) not ((((mold near2 (upper   |                        | ļ .              |
|          |       | lower) ) and (chip die wafer)) and (method   |                        |                  |
|          |       | process)) and (flipchip (flip adj chip)))  |                        |                  |
| -        | 275   | 1  | USPAT;                 | 2003/03/27 14:36 |
|          |       | die wafer)) and (method process)) and  | US-PGPUB;              |                  |
|          |       | (bump ball)) not ((((mold near2 (upper   | EPO; JPO;              | ì                |
|          |       | lower) ) and (chip die wafer)) and (method   | DERWENT                |                  |
|          |       | process)) and (flipchip (flip adj chip)))) and (releasable released release                    | 1                      |                  |
|          |       | •  |                        |                  |
| _        | 10    | releasing)   | IICDAT.                | 2003/03/27 14:43 |
| _        | 10    | (((((mold near2 (upper lower) ) and (chip die wafer)) and (method process)) and                | USPAT;<br>US-PGPUB;    | 2003/03/2/ 14:43 |
|          |       | (bump ball)) not (((mold near2 (upper  | EPO; JPO;              |                  |
|          |       | lower) ) and (chip die wafer)) and (method   | DERWENT                | 1                |
|          |       | process)) and (flipchip (flip adj chip))))   | DERWENT                |                  |
|          |       | and ((releasable released release  |                        | 1                |
|          |       | releasing) near1 (film layer tape))  |                        | ļ                |
| _        | 2     |  | USPAT                  | 2003/03/27 14:41 |
| _        | 16    | ("4044984"   "4236689"   "4332537"   | USPAT                  | 2003/03/27 14:41 |
|          |       | "4442056"   "4470786"   "4697784"  | Į.                     |                  |
|          |       | "4779835"   "5059105"   "5118271"  |                        |                  |
|          |       | "5218759"   "5429488"   "5484274"  |                        |                  |
|          |       | "5626886"   "5639695"   "5693572"  | }                      | )                |
|          |       | "5779958").PN.   |                        |                  |
| -        | 265   | ((((((mold near2 (upper lower) ) and (chip   | USPAT;                 | 2003/03/27 14:43 |
|          |       | die wafer)) and (method process)) and  | US-PGPUB;              |                  |
|          |       | (bump ball)) not ((((mold near2 (upper   | EPO; JPO;              | ļ                |
|          |       | lower) ) and (chip die wafer)) and (method   | DERWENT                |                  |
|          |       | <pre>process)) and (flipchip (flip adj chip)))) and (releasable released release</pre>         |                        | [                |
|          |       | releasing)) not (((((mold near2 (upper   |                        |                  |
|          |       | lower) ) and (chip die wafer)) and (method   |                        |                  |
|          |       | process)) and (bump ball)) not (((mold   | Ì                      | ]                |
|          |       | near2 (upper lower) ) and (chip die  |                        |                  |
| <b>,</b> |       | wafer)) and (method process)) and  | 1                      | j                |
|          |       | (flipchip (flip adj chip)))) and   |                        |                  |
| l        |       | ((releasable released release releasing)   | 1                      |                  |
|          |       | nearl (film layer tape)))  |                        |                  |
| -        | 1     |  | USPAT;                 | 2003/05/08 09:32 |
|          |       |  | US-PGPUB;              |                  |
|          | İ     |  | EPO; JPO;              |                  |
| 1        |       |  | DERWENT                | 1                |
| -        | 40999 | mold near2 (upper lower)   | USPAT;                 | 2003/05/08 09:41 |
|          |       |  | US-PGPUB;              |                  |
| ľ        |       |  | EPO; JPO;              |                  |
|          |       |  | DERWENT                |                  |
| -        | 1694  | (mold near2 (upper lower)) and   | USPAT;                 | 2003/05/08 09:42 |
|          | !     | semiconductor and (chip die wafer)   | US-PGPUB;              | [                |
|          |       |  | EPO; JPO;              | 1                |
| _ [      | 446   | //mold near? (upper lever)) and  | DERWENT                | 2003/05/00 00:45 |
| -        | 440   | ((mold near2 (upper lower)) and semiconductor and (chip die wafer)) and                        | USPAT;                 | 2003/05/08 09:45 |
|          |       | (leadframe (lead near1 (inner outer)))   | US-PGPUB;<br>EPO; JPO; | ]                |
|          | į     | (readifame (read Heart (Hiller Odder)))  | DERWENT                |                  |
|          |       |  | I PICTANETAT           | 1                |

| ſ——·— | 7 3 0 E | ///mald nany2 (unner levent) and  | TICDAM.                | T 2002 (05 (00 12.10                   |
|-------|---------|---|------------------------|--|
| -     | 395     | (((mold near2 (upper lower)) and  | USPAT;                 | 2003/05/08 12:18                       |
|       |         | semiconductor and (chip die wafer)) and   (leadframe (lead nearl (inner outer)))) | US-PGPUB;<br>EPO; JPO; | 1                                      |
|       |         | and (sealing sealed encapsulant   | DERWENT                |  |
|       | 1       | encapsulating encapsulated)   | DEKWENT                | 1                                      |
| _     | 369     | ((((mold near2 (upper lower)) and   | USPAT;                 | 2003/05/08 09:47                       |
|       |         | semiconductor and (chip die wafer)) and   | US-PGPUB;              | 2000,00,00                             |
|       |         | (leadframe (lead near1 (inner outer))))   | EPO; JPO;              |  |
|       |         | and (sealing sealed encapsulant   | DERWENT                |  |
| 1     |         | encapsulating encapsulated)) and (method  |                        | 1                                      |
| 1     |         | process)  |                        | ĺ                                      |
| -     | 122     | (((((mold near2 (upper lower)) and  | USPAT;                 | 2003/05/08 09:47                       |
| 1     | 1       | semiconductor and (chip die wafer)) and   | US-PGPUB;              |  |
|       |         | (leadframe (lead near1 (inner outer))))   | EPO; JPO;              |  |
| 1     |         | and (sealing sealed encapsulant   | DERWENT                |  |
|       | 1       | encapsulating encapsulated)) and (method  |                        |  |
| İ     |         | process)) and ((die mounting) adj pad)  |                        | 0000 (05 (00 00 50                     |
| -     | 53      | 5474958.URPN.   | USPAT                  | 2003/05/08 09:52                       |
| -     | 0       | 6472252.URPN.   | USPAT                  | 2003/05/08 09:59                       |
| -     | 36      | ("4313718"   "4697784"   "4881884"  | USPAT                  | 2003/05/08 09:59                       |
| 1     |         | "4944908"   "5147821"   "5355283"  <br>"5362679"   "5405255"   "5406699"          |                        |  |
|       | 1       | "5467253"   "5468999"   "5474958"   |                        | į.                                     |
|       |         | "5477611"   "5479051"   "5490324"   |                        |  |
|       | 1       | "5506756"   "5508565"   "5527743"   |                        | Į.                                     |
|       |         | "5543658"   "5545922"   "5556807"   |                        |  |
|       |         | "5596227"   "5609889"   "5626886"   |                        |  |
|       | i       | "5656549"   "5663106"   "5665281"   |                        |  |
|       |         | "5688716"   "5766649"   "5766650"   |                        | 1                                      |
| İ     |         | "5817545"   "5876765"   "5923959"   |                        |  |
|       | ļ       | "5928595"   "6117382"   "6281588").PN.  |                        | 1                                      |
| _     | 3       | 6117382.URPN.   | USPAT                  | 2003/05/08 10:01                       |
| -     | 20      | ("5034350"   "5114880"   "5147815"  | USPAT                  | 2003/05/08 10:02                       |
|       |         | "5222014"   "5239806"   "5313365"   |                        |  |
| }     | }       | "5331205"   "5366364"   "5458694"   |                        |  |
|       |         | "5488257"   "5578261"   "5597643"   |                        |  |
| 1     | }       | "5598034"   "5608262"   "5609889"   |                        |  |
|       |         | "5614441"   "5615089"   "5646829"   |                        |  |
|       |         | "5755914"   "5830781").PN.  |                        |  |
| -     | 20      | ("5034350"   "5114880"   "5147815"  | USPAT                  | 2003/05/08 10:04                       |
| 1     |         | "5222014"   "5239806"   "5313365"   | 1                      | 1                                      |
|       |         | "5331205"   "5366364"   "5458694"  <br>  "5488257"   "5578261"   "5597643"        |                        |  |
|       | 1       | "5598034"   "5608262"   "5609889"   | 1                      |  |
|       | ĺ i     | "5614441"   "5615089"   "5646829"   |                        |  |
|       |         | 3614441   |                        | )                                      |
|       | 7       | 5923959.URPN.   | USPAT                  | 2003/05/08 10:05                       |
| -     | 20      | ("5355283"   "5362679"   "5406699"  | USPAT                  | 2003/05/08 10:10                       |
|       |         | "5467253"   "5468999"   "5474958"   |                        | -, -, -, -, -, -, -, -, -, -, -, -, -, |
|       |         | "5477611"   "5479051"   "5490324"   |                        | 1                                      |
| 1     |         | "5506756"   "5508565"   "5527743"   |                        |  |
| ]     |         | "5543658"   "5545922"   "5556807"   |                        |  |
|       |         | "5596227"   "5609889"   "5656549"   |                        | 1                                      |
|       | ]       | "5663106"   "5688716").PN.  |                        |  |
| [ -   | 21      | 5609889.URPN.   | USPAT                  | 2003/05/08 10:12                       |
| -     | 0       | 6428300.URPN.   | USPAT                  | 2003/05/08 10:13                       |
| -     | 29      | ("3505446"   "3685784"   "3991146"  | USPAT                  | 2003/05/08 10:13                       |
|       |         | "4184835"   "4464322"   "4470786"   |                        |  |
|       |         | "4618466"   "4770833"   "4954308"   |                        |  |
| ]     |         | "5049344"   "5049526"   "5110515"   |                        |  |
| [     | 1       | "5174941"   "5326243"   "5344600"   |                        |  |
|       |         | "5366368"   "5429488"   "5451153"   |                        |  |
| Į l   |         | "5480296"   "5523038"   "5558883"   |                        |  |
|       |         | "5609889"   "5626886"   "5650177"  <br>"5714106"   "5708070"   "5888471"          |                        |  |
| 1     | [ .     | "5714106"   "5798070"   "5989471"   |                        |  |
| _     | 26      | "6030569"   "6224360").PN.<br>  5817545.URPN.                                     | HCDAT                  | 2002/05/09 10:10                       |
| [ _   | 0       | 5817545.URPN.<br>  6558982.URPN.  | USPAT<br>USPAT         | 2003/05/08 10:18 2003/05/08 10:19      |
| _     | 6       | ("5817545"   "5874324"   "5998243"  | USPAT                  | 2003/05/08 10:19                       |
| į (   |         | "6204095"   "6329224"   "6335221").PN.  | OSERI                  | 2003/03/08 10:19                       |
| L     | L       |   |                        | _1                                     |

|     | 36     | ("3930114"   "4043027"   "4437141"  | USPAT     | 2003/05/08 10:23     |
|-----|--------|---|-----------|----------------------|
|     |        | "4455274"   "4460537"   "4470786"   |           |                      |
|     |        | "4688152"   "4778641"   "4823234"   |           |                      |
|     |        | "4859722"   "4861251"   "4868349"   |           |                      |
| )   |        | "4890152"   "4893172"   "4935581"   |           |                      |
|     |        | "4954877"   "4954878"   "4961105"   | •         |                      |
| 1   |        | "4972253"   "4975765"   "5019673"   |           | ŀ                    |
|     |        | "5049526"   "5093282"   "5108955"   |           |                      |
| Ì   |        | "5132778"   "5136366"   "5153385"   |           |                      |
|     |        | "5191511"   "5216278"   "5218759"   |           |                      |
| ļ   |        | "5241133"   "5296738"   "5328870"   | <b>\</b>  | 1                    |
|     |        | "5355283"   "5370517"   "5395226").PN.                                    |           |                      |
| 1   | 40     |   | USPAT     | 2003/05/08 10:26     |
| _   | 40     | 5108955.URPN.<br>  ("4266239"   "4541005"   "4778641"                     |           | 2003/05/08 10:20     |
| _   | ′      |   | USPAT     | 2003/03/08 10:43     |
|     |        | "4822550"   "4823234"   "4868638"   |           |                      |
| į   |        | "4890152").PN.  |           | 1 0000 105 100 30 30 |
| _   | 3      | 6081978.URPN.   | USPAT     | 2003/05/08 12:10     |
| -   | 3      | ("5336272"   "6001671"   "6033933").PN.                                   | USPAT     | 2003/05/08 12:11     |
| -   | 113    | [   | USPAT;    | 2003/05/08 12:18     |
|     |        | semiconductor and (chip die wafer)) and                                   | US-PGPUB; |                      |
| )   | )      | (leadframe (lead nearl (inner outer))))                                   | EPO; JPO; | 1                    |
|     |        | and (sealing sealed encapsulant   | DERWENT   |                      |
| 1   | 1      | encapsulating encapsulated)) and (vent                                    | 1         | 1                    |
|     |        | vacuum)   |           |                      |
| -   | 389176 | "113" not (((((mold near2 (upper lower))                                  | USPAT;    | 2003/05/08 12:19     |
|     | _      | and semiconductor and (chip die wafer))                                   | US-PGPUB; |                      |
|     | 1      | and (leadframe (lead nearl (inner   | EPO; JPO; | ļ .                  |
| 1   |        | outer)))) and (sealing sealed encapsulant                                 | DERWENT   |                      |
| l   | [      | encapsulating encapsulated)) and (method                                  |           |                      |
|     |        | process)) and ((die mounting) adj pad))                                   |           |                      |
| l _ | 91     |   | USPAT;    | 2003/05/08 12:19     |
|     | 1      | semiconductor and (chip die wafer)) and                                   | US-PGPUB; | 2003,00,00 12.13     |
|     |        | · · · · · · · · · · · · · · · · · ·                                       | EPO; JPO; |                      |
|     | 1      | (leadframe (lead nearl (inner outer))))                                   |           |                      |
|     |        | and (sealing sealed encapsulant   | DERWENT   |                      |
| 1   | 1      | encapsulating encapsulated)) and (vent                                    |           | )                    |
|     |        | vacuum)) not (((((mold near2 (upper                                       |           |                      |
| i   | }      | lower)) and semiconductor and (chip die                                   |           | <b>\</b>             |
|     |        | wafer)) and (leadframe (lead nearl (inner                                 |           |                      |
| }   | }      | outer)))) and (sealing sealed encapsulant                                 |           |                      |
|     |        | encapsulating encapsulated)) and (method                                  |           | 1                    |
| ļ   | ļ      | process)) and ((die mounting) adj pad))                                   | ;         | !                    |
| -   | 25     | 5147821.URPN.   | USPAT     | 2003/05/08 12:24     |
| -   | 2      | ("4866506"   "4944908").PN.   | USPAT     | 2003/05/08 12:26     |
| _   | 25     | 5147821.URPN.   | USPAT     | 2003/05/08 13:43     |
| _   | 53     | 5474958.URPN.   | USPAT     | 2003/05/08 13:44     |
| -   | 4      | 5776800.URPN.   | USPAT     | 2003/05/08 13:45     |
| _   | 5      | ("5101324"   "5130889"   "5309026"  | USPAT     | 2003/05/08 13:45     |
| 1   | ]      | "5394298"   "5474958").PN.  |           | ]                    |
| _   | 2      | 5874319.URPN.   | USPAT     | 2003/05/08 13:48     |
| _   | 21     | 3074319.0KFN.<br>  ("3777365"   "3811182"   "4881885"                     | USPAT     | 2003/05/08 13:48     |
|     |        | "4932883"   "5147821"   "5173451"   | JULAI     | 2000,00,00 13.40     |
| 1   |        | "4932883"   "5147821"   5173451"  <br>  "5203401"   "5237269"   "5322207" |           | 1                    |
|     |        |   |           | 1                    |
|     | 1      | "5336649"   "5367253"   "5378981"   |           | ]                    |
|     |        | "5424652"   "5459351"   "5474958"   |           |                      |
| Į   | Į.     | "5475317"   "5489538"   "5548884"   |           |                      |
|     |        | "5568057"   "5589781"   "5591649").PN.                                    |           |                      |
| -   | 2      | ("4866506"   "4944908").PN.   | USPAT     | 2003/05/08 13:53     |
| -   | 2      | ("4866506"   "4944908").PN.   | USPAT     | 2003/05/08 13:53     |
| -   | 5      | "6081978 <b>"</b>   | USPAT;    | 2003/05/12 09:17     |
| ]   |        |   | US-PGPUB; | 1                    |
|     |        |   | EPO; JPO; |                      |
|     |        |   | DERWENT   | j                    |
| _   | 3      | ("5336272"   "6001671"   "6033933").PN.                                   | USPAT     | 2003/05/12 08:46     |
| _   | 740    | (memory adj chip) near3 array   | USPAT;    | 2003/05/12 09:36     |
|     |        | , and onep, money array   | US-PGPUB; |                      |
|     |        |   | EPO; JPO; | , (                  |
|     |        |   | DERWENT   |                      |
|     | 471    | ((memory adj chip) near3 array) and                                       | USPAT;    | 2003/05/12 09:18     |
| · . | 4/1    | semiconductor   | 1         | 2003/03/12 03.18     |
|     |        | Semiconductor   | US-PGPUB; | ,                    |
|     |        |   | EPO; JPO; | 1                    |
| 1   | l      |   | DERWENT   | i i                  |

|     |             |  | T           | 17                 |
|-----|-------------|--|-------------|--------------------|
| ļ - | 137         | ((memory adj chip) near3 array) and                | USPAT;      | 2003/05/12 09:20   |
|     |             | (semiconductor nearl (package device))             | US-PGPUB;   |                    |
|     | 1           |  | EPO; JPO;   | 1                  |
|     |             |  | DERWENT     | 1                  |
| -   | 8           | ((memory adj chip) near3 array) with known         | USPAT;      | 2003/05/12 09:37   |
|     | 1           |  | US-PGPUB;   |                    |
| 1   | 1           |  | EPO; JPO;   |                    |
|     |             |  | DERWENT     |                    |
| -   | 1406        | (memory near chip) near4 array                     | USPAT;      | 2003/05/12 09:36   |
|     |             |  | US-PGPUB;   |                    |
|     |             |  | EPO; JPO;   |                    |
|     | ļ           |  | DERWENT     | Į.                 |
| _   | 15          | ((memory near chip) near4 array) with              | USPAT;      | 2003/05/12 09:37   |
|     | 1           | known  | US-PGPUB;   | 2003/03/12 09.37   |
|     |             | KIIOWII  |             | 1                  |
|     | 1           |  | EPO; JPO;   |                    |
|     | _           |  | DERWENT     | 0000 /05 /10 00 00 |
| _   | 7           | ( ( (  | USPAT;      | 2003/05/12 09:37   |
|     |             | known) not (((memory adj chip) near3               | US-PGPUB;   | 1                  |
|     |             | array) with known)                                 | EPO; JPO;   | 1                  |
|     |             |  | DERWENT     | İ                  |
| -   | 2102        | (tab near3 lead) and semiconductor and             | USPAT;      | 2003/05/19 08:33   |
|     |             | (chip die wafer)                                   | US-PGPUB;   | İ                  |
|     | 1           |  | EPO; JPO;   | ì                  |
|     |             |  | DERWENT     | 1                  |
| -   | 1640        | ((tab near3 lead) and semiconductor and            | USPAT;      | 2003/05/19 08:36   |
|     |             | (chip die wafer) ) and (lead with                  | US-PGPUB;   | 1                  |
|     | 1           | (electrode bump ball terminal pad))                | EPO; JPO;   | ]                  |
|     |             | (ozoonowo zamp warz dorminaz pad, )                | DERWENT     |                    |
| _   | 123         | (((tab near3 lead) and semiconductor and           | USPAT;      | 2003/05/19 08:37   |
|     | 123         | (chip die wafer) ) and (lead with                  | US-PGPUB;   | 2003/03/13 00:3/   |
|     |             | (electrode bump ball terminal pad))) and           | EPO; JPO;   |                    |
|     |             |  | DERWENT     | Į.                 |
|     |             | (conductive nearl (vias (through adj               | DEKWENI     |                    |
|     |             | hole)))  | HODE        | 2002/05/10 00 30   |
| _   | 94          | ((((0000 000000000000000000000000000000            | USPAT;      | 2003/05/19 08:38   |
|     | 1           | (chip die wafer) ) and (lead with                  | US-PGPUB;   | 1                  |
|     |             | (electrode bump ball terminal pad))) and           | EPO; JPO;   | 1                  |
|     | }           | (conductive near1 (vias (through adj               | DERWENT     | 1                  |
|     |             | hole)))) and (seal sealed sealing                  | 1           | 1                  |
|     |             | encapsulant encapsulated encapsulating)            |             | }                  |
| -   | 43          | (((((000 11000 2000) 2110 00112001100000 21110     | USPAT;      | 2003/05/19 08:38   |
|     | Ì           | (chip die wafer) ) and (lead with                  | US-PGPUB;   |                    |
|     |             | (electrode bump ball terminal pad))) and           | EPO; JPO;   |                    |
|     |             | (conductive near1 (vias (through adj               | DERWENT     |                    |
|     | į           | hole)))) and (seal sealed sealing                  |             |                    |
|     |             | encapsulant encapsulated encapsulating))           | 1           |                    |
|     |             | and (stacked stacking)                             |             |                    |
|     | <del></del> | Tarrier (= and and and and and and and and and and | <del></del> | <del></del>        |